

and replace that text with the following --

RELATED APPLICATIONS

This application is a continuation of U.S. Application Ser. No. 08/944,135, filed on October 6, 1997, and issued as U.S. Patent No. 5,952,050; which is a continuation of U.S. Application Serial Number 08/618,072, filed February 27, 1996 and now abandoned. --

IN THE CLAIMS

Please cancel claims 1 and 34-43.

Please amend the following claims.

SUB  
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12. (Once amended) A processor for a spin coating device including a chuck defining a wafer accommodation area [plane], comprising:

at least one solvent dispenser; and

a suction mechanism generally around said at least one solvent dispenser and offset from said wafer accommodation area during an operational mode of said device [plane].

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13. (Once amended) The processor in claim 12, wherein said at least one solvent dispenser further comprises:

a first solvent dispenser on a first side of said wafer accommodation area [plane]; and

a second solvent dispenser on a second side of said wafer accommodation area [plane].

14. (Once amended) A bead remover for a wafer [having an edge], comprising:

a negative pressure mechanism configured to be spaced from said wafer while  
operating upon said wafer [edge]; and

a solvent-dispensing mechanism aligned with said negative pressure mechanism.